Session E

Manufacturing Methods, Production and Packaging

Chairman:

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The papers in this session demonstrate the increasing sophistication and maturing of microwave applications and the necessity to consider the incorporate manufacturing and packaging yield consideration into the design process. New multichip module (MCM) design, modeling and simulation capabilities will link electrical, thermal and geometrical characteristics and parameters to minimize the number of design iterations and reduce manufacturing costs. Such tools will be used to develop assemblies of MCMs, such as phased array antennas, where complex interfaces and interconnection are required. The development of well controlled processes and production techniques are required to support flexible manufacturing.

11:00 a.m.–12:00 p.m., Tuesday, June 15, 1993
Room 218/219